



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Free-standing heat dissipator and clip assembly

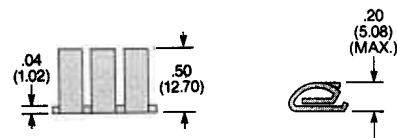
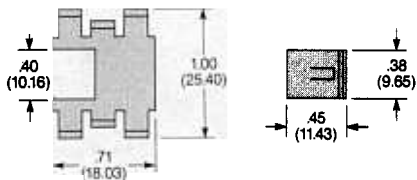
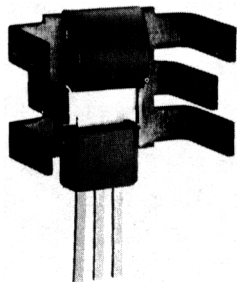
- Beryllium copper clip is designed to provide high clamping pressure, which assures low thermal resistance between dissipator and semiconductor, allowing a 150% power increase in natural convection to more than 400% in forced air.

- Clip may be used alone to attach semiconductor to a customer designed heat conduction plane.
- Free-standing assembly can be mounted either vertically or horizontally on board

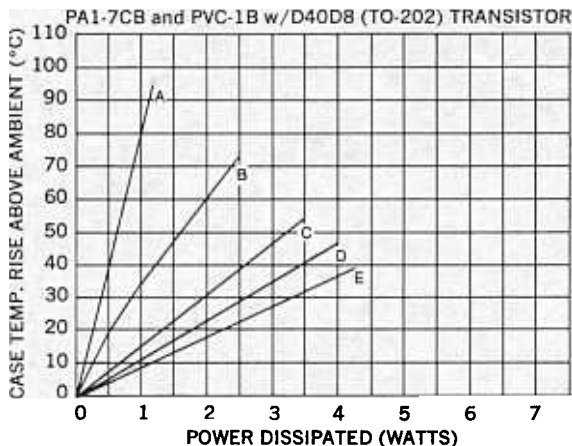
— requires no special tools or mounting hardware.

- Clip's spring design firmly attaches to device and dissipator, stays attached even in severe shock and vibration environments.

PA1-7



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

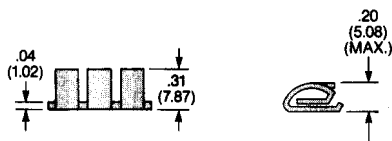
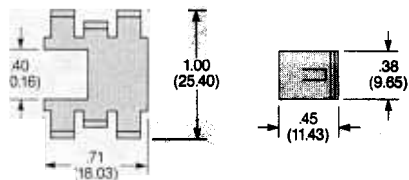
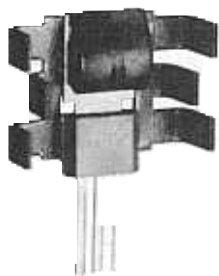
- A. N.C. Horiz. Device Only Freestanding.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

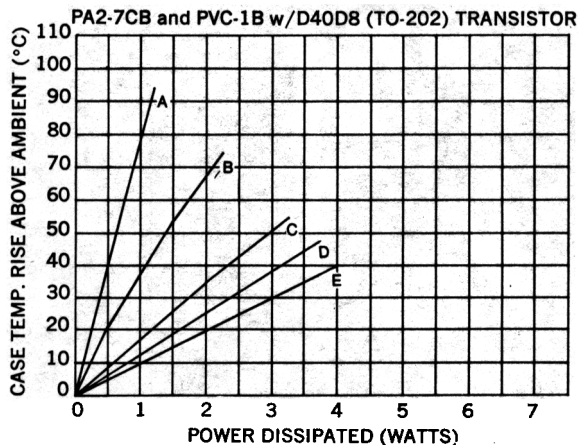
Ordering Information

ITEM	IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize		
Dissipator	PA1-7U	N/A	PA1-7CB	PA1-7B	TO-202	2.0
Clip	PVC-1U	PVC-1B	N/A	N/A	TO-202	0.7

PA2-7



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Freestanding.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

Ordering Information

ITEM	IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize		
Dissipator	PA2-7U	N/A	PA2-7CB	PA2-7B	TO-202	1.5
Clip	PVC-1U	PVC-1B	N/A	N/A	TO-202	0.7